

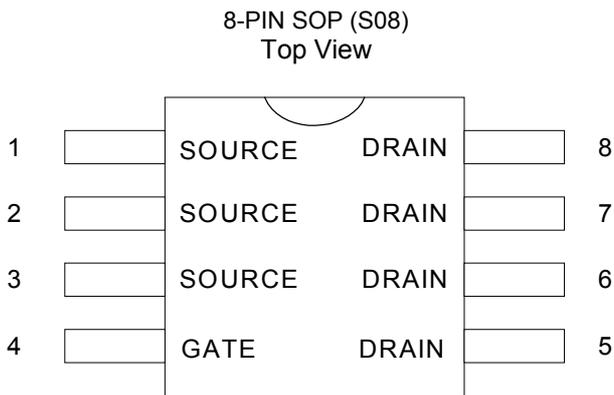
STRUCTURE

- ◆ Silicon N-channel MOSFET

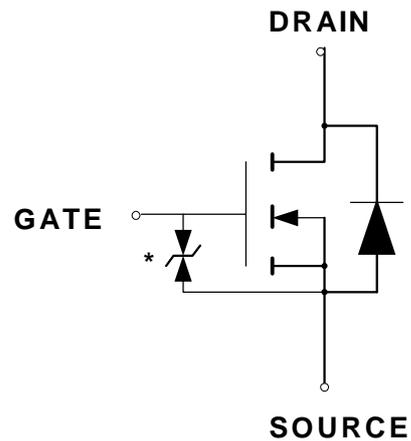
FEATURES

- ◆ Low Qg
- ◆ Low on-resistance
- ◆ Excellent resistance to damage from static electricity

PIN CONFIGURATION



SYMBOL



N-Channel MOSFET

* Gate Protection Diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use a protection circuit when the fixed voltage are exceeded.

ORDERING INFORMATION

Part Number	Package
CMT4410	8-PIN SOP (S08)

ABSOLUTE MAXIMUM RATINGS (T_a = 25°C)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DS}	30	V
Drain to Current – Continuous (at 25°C)	I _D	10	A
– Pulsed*	I _{DP}	40	
Reverse Drain to Current – Continuous (at 25°C)	I _R	10	A
– Pulsed*	I _{DRP}	40	
Source Current (Body Diode) – Continuous (at 25°C)	I _S	1.3	A
– Pulsed*	I _{SP}	5.2	
Gate-to-Source Voltage – Continue	V _{GS}	±20	V
Total Power Dissipation (T _c = 25°C)	P _D	2.0	W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Channel Temperature	T _{ch}	150	°C

* Pw ≤ 10ms, Duty cycle ≤ 1%

THERMAL RESISTANCE ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth(ch-A)	62.5	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_a = 25^\circ\text{C}$.

Characteristic		Symbol	CMT4410			Units
			Min	Typ	Max	
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$)		$V_{(BR)DSS}$	30			V
Zero Gate Voltage Drain Current ($V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$)		I_{DSS}			10	$\mu\text{ A}$
Gate-Source Leakage Current ($V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$)		I_{GSS}			± 10	$\mu\text{ A}$
Gate Threshold Voltage ($V_{DS} = 10\text{ V}$, $I_D = 1\text{ mA}$)		$V_{GS(th)}$	1.0		2.5	V
Static Drain-Source On-Resistance ($V_{GS} = 10\text{ V}$, $I_D = 10\text{ A}$) ($V_{GS} = 4.5\text{ V}$, $I_D = 10\text{ A}$) ($V_{GS} = 4.0\text{ V}$, $I_D = 10\text{ A}$)		$R_{DS(on)}$		9 13 15	12 18 20	m Ω
Forward Transfer Admittance ($V_{DS} = 10\text{ V}$, $I_D = 10\text{ A}$) *		$ Y_{FS} $	10			mhos
Input Capacitance	$(V_{DS} = 10\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V})^*$	C_{iss}		1750		pF
Output Capacitance		C_{oss}		950		pF
Reverse Transfer Capacitance		C_{rss}		450		pF
Turn-On Delay Time	$(V_{DD} = 15\text{ V}$, $I_D = 5\text{ A}$, $V_{GS} = 10\text{ V}$, $R_L = 3\Omega$, $R_{GS} = 10\Omega$) *	$t_{d(on)}$		20		ns
Rise Time		t_r		55		ns
Turn-Off Delay Time		$t_{d(off)}$		100		ns
Fall Time		t_f		70		ns
Source-Drain Reverse Recovery Time **	$I_F = 2.3\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$	t_{rr}		50	80	ns
Total Gate Charge	$(V_{DD} = 15\text{ V}$, $I_D = 10\text{ A}$, $V_{GS} = 10\text{ V})^*$	Q_g		44.8	89.6	nC
Gate-Source Charge		Q_{gs}		5.9		nC
Gate-Drain Charge		Q_{gd}		12.2		nC

* Pulsed

BODY DIODE CHARACTERISTICS (SOURCE-DRAIN)

Unless otherwise specified, $T_a = 25^\circ\text{C}$.

Characteristic		Symbol	CMT4410			Units
			Min	Typ	Max	
Forward Voltage ($V_{GS} = 0\text{ V}$, $I_S = 5.2\text{ A}$)*		V_{SD}			1.5	V
Reverse Recovery Time	$(V_{GS} = 0\text{ V}$, $I_{DR} = 5.2\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s})^*$	t_{rr}		240		ns
Reverse Recovery Charge		Q_{rr}		310		nC

TYPICAL ELECTRICAL CHARACTERISTICS

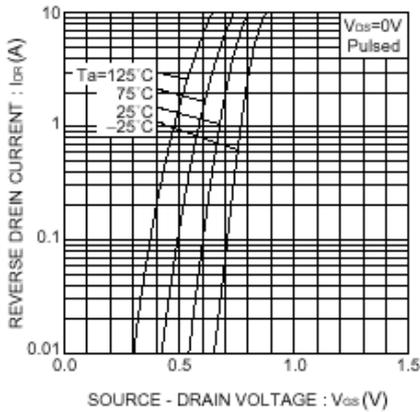


Fig.1 Reverse Drain Current vs. Source - Drain Voltage

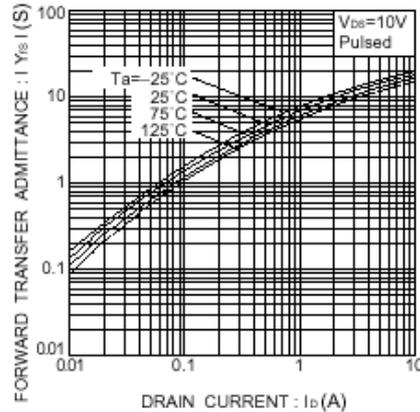


Fig.2 Forward Transfer Admittance vs. Drain Current

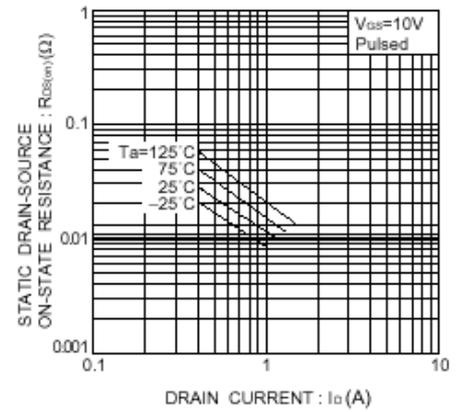


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current (I)

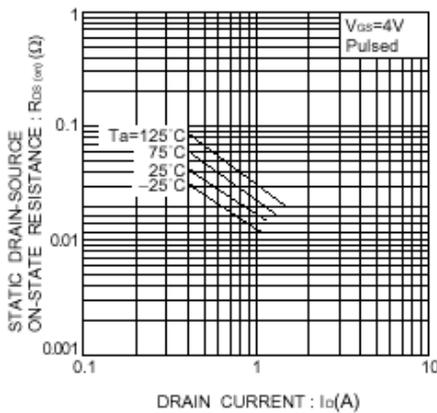


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (II)

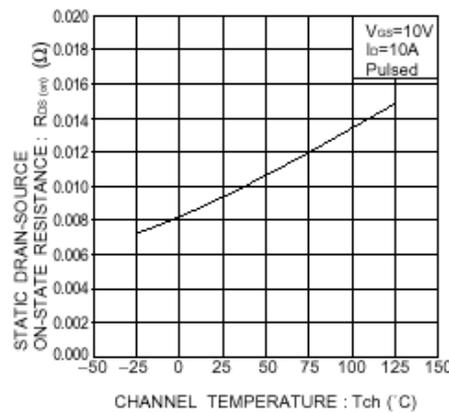


Fig.5 Static Drain-Source On-State Resistance vs. Channel Temperature

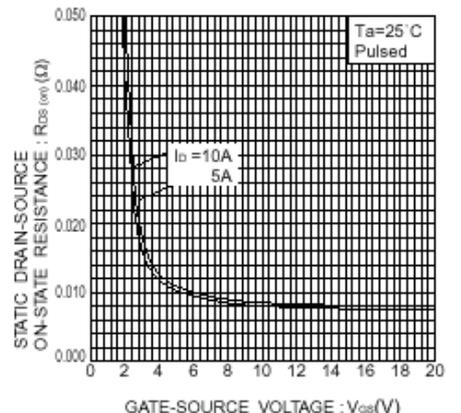


Fig.6 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

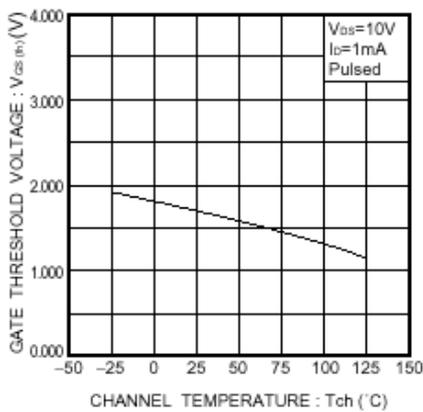


Fig.7 Gate Threshold Voltage vs. Channel Temperature

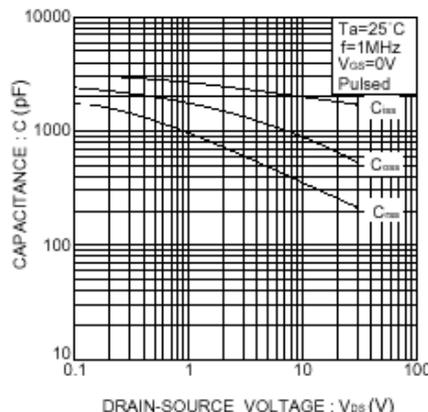


Fig.8 Typical Capacitance vs. Drain-Source Voltage

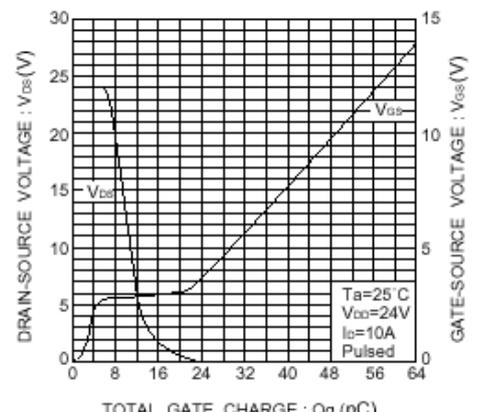


Fig.9 Dynamic Input Characteristics

TYPICAL ELECTRICAL CHARACTERISTICS (Conti.)

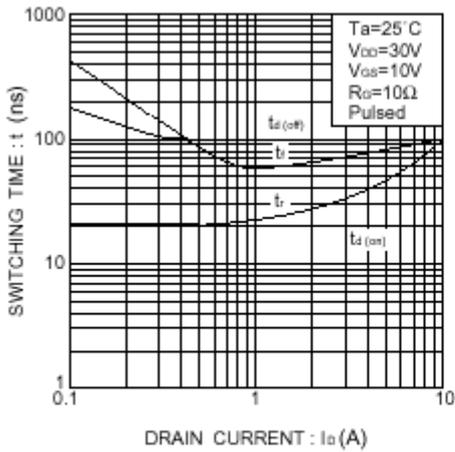


Fig.10 Switching Characteristics

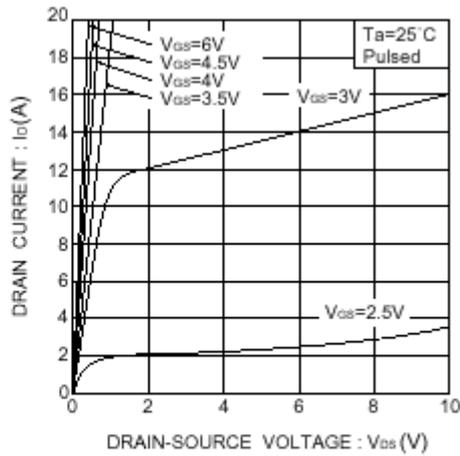


Fig.11 Typical Output Characteristics

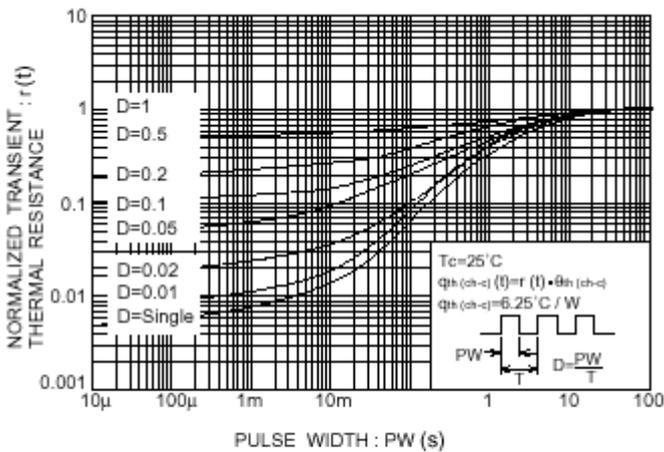
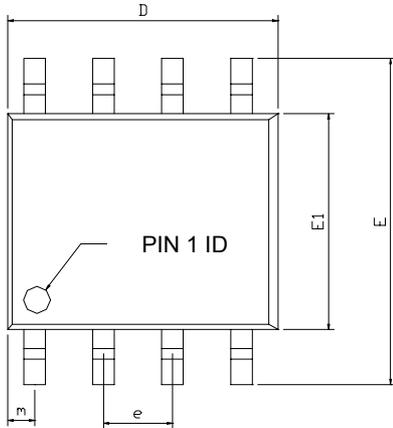


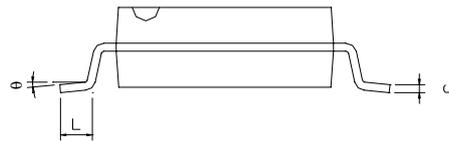
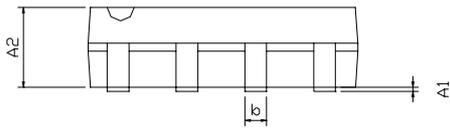
Fig.12 Normalized Transient Thermal Resistance vs. Pulse Width

PACKAGE DIMENSION

8-PIN SOP (S08)



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHS		
	MIN	NOM	MAX	MIN	NOM	MAX
A1	0.10	----	0.25	0.004	----	0.010
A2	1.40	----	1.55	0.055	----	0.061
b	0.30	----	0.51	0.012	----	0.020
C	0.15	----	0.26	0.006	----	0.010
D	4.60	----	5.06	0.169	----	0.199
E	5.79	----	6.20	0.228	----	0.244
E1	3.76	----	4.01	0.148	----	0.158
e	----	1.27	----	----	0.050	----
L	0.38	----	0.69	0.015	----	0.035
m	0.43	----	0.69	0.017	----	0.027
θ	0°	----	8°	0°	----	8°



IMPORTANT NOTICE

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